# Field Stop Trench IGBT, 20 A, 650 V

## FGAF20S65AQ

Using novel field stop IGBT technology, ON Semiconductor's new series of field stop 4th generation of RC IGBTs offer the optimum performance for PFC applications and welder where low conduction and switching losses are essential.

#### **Features**

- Maximum Junction Temperature: T<sub>J</sub> = 175°C
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(Sat)} = 1.4 \text{ V (Typ.)}$  @  $I_C = 20 \text{ A}$
- 100% of the Parts Tested for I<sub>LM</sub> (Note 1)
- High Input Impedance
- Fast Switching
- Tighten Parameter Distribution
- IGBT with Monolithic Reverse Conducting Diode
- This Device is Pb-Free and is RoHS Compliant

#### **Typical Applications**

• PFC, Welder

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector to Emitter Voltage	V <sub>CES</sub>	650	V
Gate to Emitter Voltage Transient Gate to Emitter Voltage	V <sub>GES</sub>	±20 ±30	V
Collector Current $@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$	I <sub>C</sub>	40 20	Α
Pulsed Collector Current (Note 1)	I <sub>LM</sub>	60	Α
Pulsed Collector Current (Note 2)	I <sub>CM</sub>	60	Α
Diode Forward Current @T <sub>C</sub> = 25°C @ T <sub>C</sub> = 100°C	IF	20 10	Α
Pulsed Diode Maximum Forward Current	I <sub>FM</sub>	60	Α
Maximum Power Dissipation@ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	P <sub>D</sub>	75 37	W
Operating Junction / Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	$T_L$	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

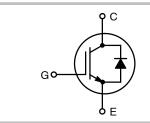
- 1.  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $I_{C}$  = 60 A,  $R_{G}$  = 23  $\Omega$ , Inductive Load, 100% Tested
- 2. Repetitive rating: pulse width limited by max. Junction temperature



#### ON Semiconductor®

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20 A, 650 V  $V_{CE(sat)} = 1.4 \text{ V (Typ.)}$ 





TO-3PF CASE 340AH

#### **MARKING DIAGRAM**



&Y = ON Semiconductor Logo = Designate space on marking &E

= 3-Digit Data Code &3

= 2-Digit Lot Traceability Code FGAF20S65AQ = Specific Device Code

#### ORDERING INFORMATION

Device	Package	Shipping	
FGAF20S65AQ	TO-3PF-3L	30 Units / Rail	

**Table 1. THERMAL CHARACTERISTICS** 

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case, for IGBT	$R_{ hetaJC}$	2	°C/W
Thermal Resistance, Junction-to-Case, for Diode	$R_{ heta JC}$	3.6	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	40	°C/W

#### **Table 2. ELECTRICAL CHARACTERISTICS** (T<sub>.1</sub> = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTIC		•		•		•
Collector-emitter breakdown voltage, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	BV <sub>CES</sub>	650	-	_	V
Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	ΔBV <sub>CES</sub> / ΔΤ <sub>J</sub>	-	0.5	_	V/°C
Collector-emitter cut-off current, gate- emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 650 V	I <sub>CES</sub>	-	-	250	μΑ
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	-	±400	nA
ON CHARACTERISTIC						
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$ , $I_C = 20$ mA	V <sub>GE(th)</sub>	2.6	5.3	6.6	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 20 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 20 A, T <sub>J</sub> = 175°C	V <sub>CE(sat)</sub>	- -	1.4 1.7	2.1 -	V
DYNAMIC CHARACTERISTIC						
Input capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$	C <sub>ies</sub>	-	1319	-	pF
Output capacitance		C <sub>oes</sub>	-	21	-	
Reverse transfer capacitance	1	C <sub>res</sub>	-	6	-	
Gate charge total	V <sub>CE</sub> = 400 V, I <sub>C</sub> = 20 A, V <sub>GE</sub> = 15 V	Qg	-	38	-	nC
Gate to emitter charge	1	Q <sub>ge</sub>	-	9	-	
Gate to collector charge	1	Q <sub>gc</sub>	-	11	-	
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					-
Turn-on delay time	T <sub>J</sub> = 25°C	t <sub>d(on)</sub>	-	16	_	ns
Rise time	$V_{CC} = 400 \text{ V}, I_{C} = 5 \text{ A}$	t <sub>r</sub>	_	6.4	_	
Turn-off delay time	$R_g = 23 \Omega$ $V_{GE} = 15 V$	t <sub>d(off)</sub>	-	109	_	1
Fall time	Inductive Load	t <sub>f</sub>	-	27	_	
Turn-on switching loss	1	E <sub>on</sub>	-	200	-	μJ
Turn-off switching loss	1	E <sub>off</sub>	-	56	_	1
Total switching loss	1	E <sub>ts</sub>	-	256	_	
Turn-on delay time	T <sub>J</sub> = 25°C	t <sub>d(on)</sub>	-	18	_	ns
Rise time	$V_{CC} = 400 \text{ V}, I_{C} = 10 \text{ A}$	t <sub>r</sub>	-	11	-	1
Turn-off delay time	$R_g = 23 \Omega$ $V_{GE} = 15 V$	t <sub>d(off)</sub>	-	102	-	1
Fall time	Inductive Load	t <sub>f</sub>	-	21	-	1
Turn-on switching loss	1	E <sub>on</sub>	-	345	-	μJ
Turn-off switching loss	1	E <sub>off</sub>	-	95	-	1
Total switching loss		E <sub>ts</sub>	_	440	_	1

Table 2. ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
SWITCHING CHARACTERISTIC, IN	IDUCTIVE LOAD		•	•	•	•
Turn-on delay time	T <sub>J</sub> = 175°C	t <sub>d(on)</sub>	_	14.4	_	ns
Rise time	$V_{CC}$ = 400 V, $I_{C}$ = 5 A $R_{q}$ = 23 $\Omega$	t <sub>r</sub>	_	6.4	_	1
Turn-off delay time	$V_{GE} = 15 \text{ V}$	t <sub>d(off)</sub>	-	118	-	
Fall time	Inductive Load	t <sub>f</sub>	-	51	_	1
Turn-on switching loss		E <sub>on</sub>	-	301	_	μJ
Turn-off switching loss		E <sub>off</sub>	-	94	_	1
Total switching loss		E <sub>ts</sub>	-	395	-	
Turn-on delay time	T <sub>J</sub> = 175°C	t <sub>d(on)</sub>	-	16	_	ns
Rise time	$V_{CC} = 400 \text{ V}, I_{C} = 10 \text{ A}$ $R_{g} = 23 \Omega$	t <sub>r</sub>	-	12	_	1
Turn-off delay time	$N_{g} = 25.52$ $V_{GE} = 15 \text{ V}$	t <sub>d(off)</sub>	-	114	_	1
Fall time	Inductive Load	t <sub>f</sub>	-	46	_	1
Turn-on switching loss		E <sub>on</sub>	-	466	_	μJ
Turn-off switching loss		E <sub>off</sub>	-	177	_	1
Total switching loss		E <sub>ts</sub>	-	643	_	1
DIODE CHARACTERISTIC						
Forward Voltage	I <sub>F</sub> = 10 A I <sub>F</sub> = 10 A, T <sub>J</sub> = 175°C	V <sub>F</sub>	-	1.3 1.3	1.6 -	V
Reverse Recovery Energy	I <sub>F</sub> = 10 A, dI <sub>F</sub> /dt = 200 A/μs	E <sub>rec</sub>	-	179	_	μJ
Diode Reverse Recovery Time	$I_F = 10 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}$ $I_F = 10 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, T_J = 175^{\circ}\text{C}$	T <sub>rr</sub>	-	235 302	-	nS
Diode Reverse Recovery Charge	$I_F = 10 \text{ A},  dI_F/dt = 200 \text{ A}/\mu\text{s}$ $I_F = 10 \text{ A},  dI_F/dt = 200 \text{ A}/\mu\text{s},  T_J = 175^{\circ}\text{C}$	Q <sub>rr</sub>	-	802 1286	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

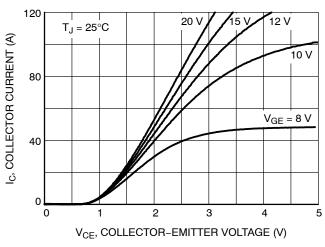


Figure 1. Typical Output Characteristics

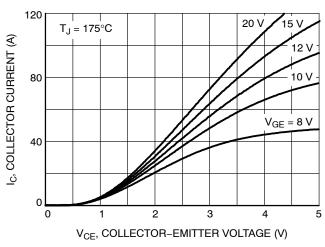


Figure 2. Typical Output Characteristics

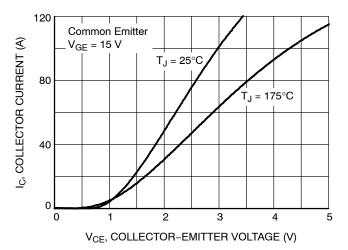


Figure 3. Typical Saturation Voltage Characteristics

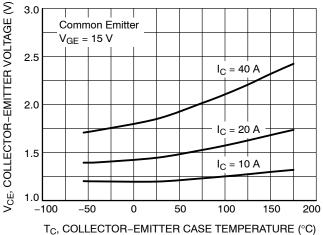


Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level

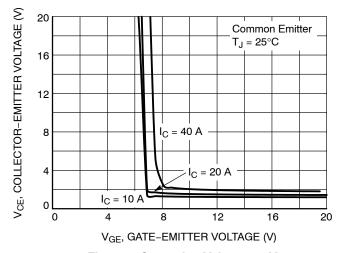


Figure 5. Saturation Voltage vs. V<sub>GE</sub>

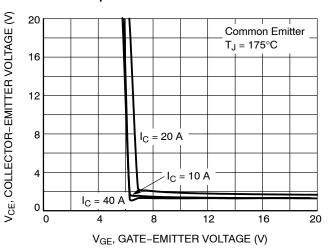


Figure 6. Saturation Voltage vs. V<sub>GE</sub>

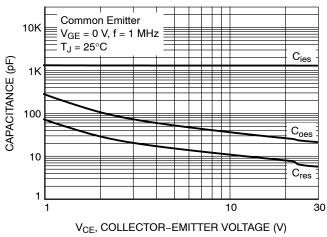


Figure 7. Capacitance Characteristics

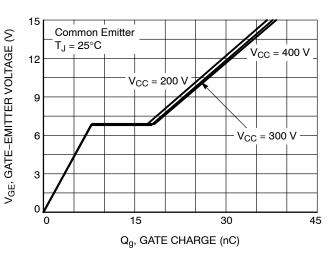


Figure 8. Gate Charge

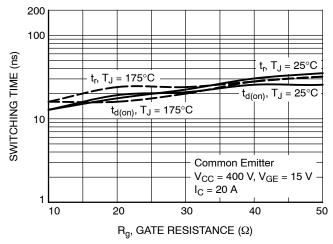


Figure 9. Turn-On Characteristics vs. Gate Resistance

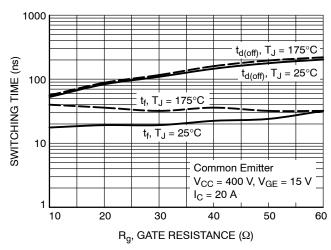


Figure 10. Turn-Off Characteristics vs. Gate Resistance

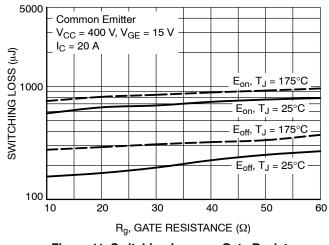


Figure 11. Switching Loss vs. Gate Resistance

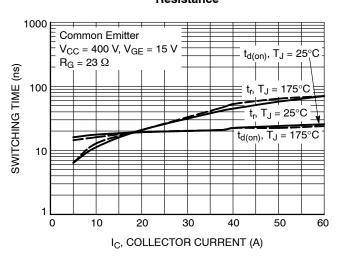


Figure 12. Turn-On Characteristics vs.
Collector Current

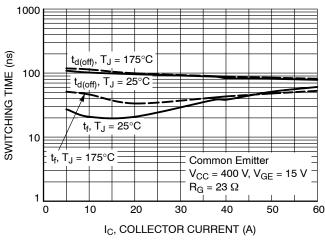


Figure 13. Turn-Off Characteristics vs.
Collector Current

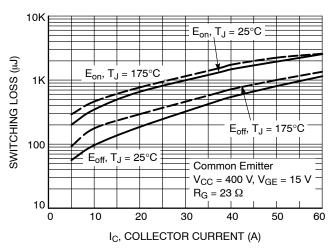


Figure 14. Switching Loss vs. Collector Current

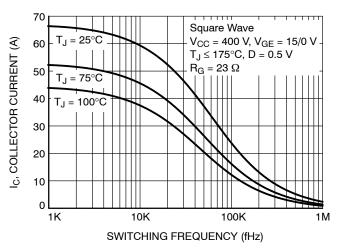


Figure 15. Load Current vs. Frequency

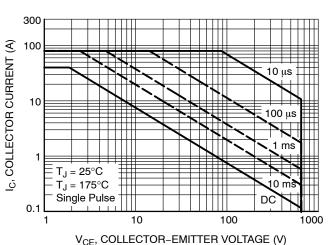


Figure 16. SOA Characteristics (FBSOA)

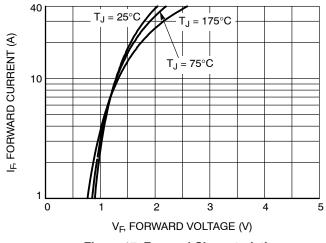


Figure 17. Forward Characteristics

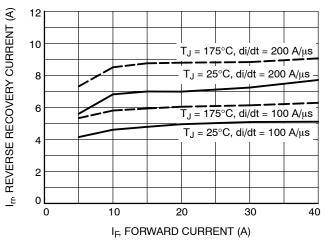


Figure 18. Reverse Recovery Current

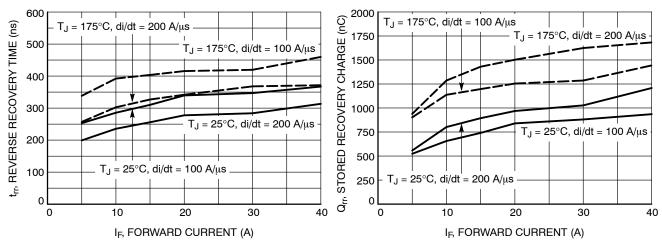


Figure 19. Reverse Recovery Time

Figure 20. Stored Charge

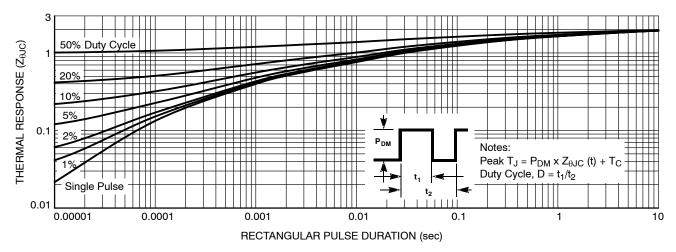


Figure 21. Transient Thermal Impedance of IGBT

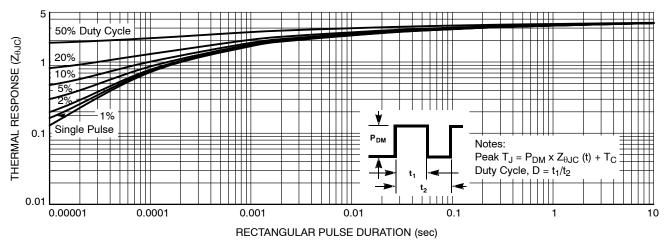
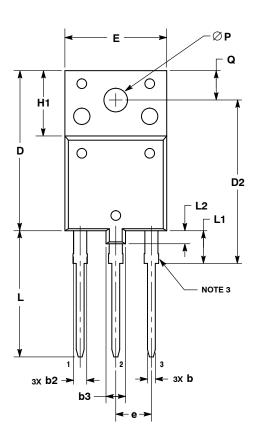


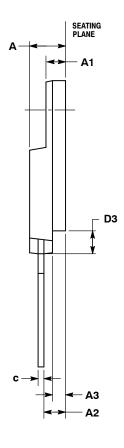
Figure 22. Transient Thermal Impedance of Diode



TO-3PF-3L CASE 340AH **ISSUE A** 

**DATE 09 JAN 2015** 





- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
  2. CONTROLLING DIMENSION: MILLIMETERS.

- 2. CONTOUR UNCONTROLLED IN THIS AREA (6 PLACES).

  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.13 PER SIDE. THES DIMENSIONS ARE TO BE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.

  5. DIMENSION b2 DOES NOT INCLUDE DAMBAR PROTRUSION.
- LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 2.20.

	MILLIMETERS			
DIM	MIN	MAX		
Α	5.30	5.70		
A1	2.80	3.20		
A2	3.10	3.50		
А3	1.80	2.20		
p	0.65	0.95		
b2	1.90	2.15		
b3	3.80	4.20		
С	0.80	1.10		
D	24.30	24.70		
D2	24.70	25.30		
D3	3.30	3.70		
Е	15.30	15.70		
е	5.35	5.55		
H1	9.80	10.20		
Г	19.10	19.50		
L1	4.80	5.20		
L2	1.90	2.20		
Р	3.40	3.80		
Ø	4.30	4.70		

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